

# N-Channel 100 V (D-S) MOSFET

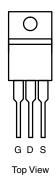
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)	
100	0.010 at V <sub>GS</sub> = 10 V	85 <sup>d</sup>	77	

### **FEATURES**

- Halogen-free According to IEC 61249-2-21 **Definition**
- TrenchFET® Power MOSFET
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



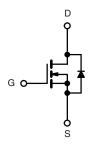
### TO-220AB



**Ordering Information:** SUP85N10-10P-GE3 (Lead (Pb)-free and Halogen-free)

### **APPLICATIONS**

Industrial



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V <sub>DS</sub>	100	V			
Gate-Source Voltage	V <sub>GS</sub>	± 20	ľ			
Continuous Drain Current (T <sub>.1</sub> = 175 °C)	T <sub>C</sub> = 25 °C	. I <sub>D</sub>	85 <sup>d</sup>	A		
Continuous Brain Gunent (1) = 175 G)	T <sub>C</sub> = 70 °C		83			
Pulsed Drain Current		I <sub>DM</sub>	240	A		
Avalanche Current		I <sub>AS</sub>	60			
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub> 180		mJ		
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	В	227 <sup>b</sup>	w		
	T <sub>A</sub> = 25 °C <sup>c</sup>	- P <sub>D</sub>	3.75			
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.55			

### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.



Parameter	Symbol	otherwise noted)  Test Conditions	Min.	Tvn	Max.	Unit
Static	Syllibol	Test Conditions	IVIIII.	Тур.	IVIAX.	Ullit
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>DS</sub> = 0 V, I <sub>D</sub> = 250 μA	100			
		$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.5		4.5	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$ $V_{DS} = 0 \text{V},  V_{GS} = \pm 20 \text{V}$	2.5			4
Gate-Body Leakage	I <sub>GSS</sub>	20 40			± 250	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μА
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	120			A
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		0.0080	0.0100	Ω
	- DS(011)	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 125 ^{\circ}\text{C}$		0.0146	0.0185	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		70		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 50 V, f = 1 MHz		4660		pF
Output Capacitance	C <sub>oss</sub>			315		
Reverse Transfer Capacitance	C <sub>rss</sub>			150		
Total Gate Charge <sup>c</sup>	$Q_g$			77	120	nC
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 75 \text{ A}$		25		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			20		
Gate Resistance	$R_{g}$	f = 1 MHz	0.25	1.2	2.4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_{L} = 0.67 \Omega$		12	20	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 75 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		25	40	
Fall Time <sup>c</sup>	t <sub>f</sub>			8	15	
Drain-Source Body Diode Characteri	stics T <sub>C</sub> = 25	°Cp				
Continuous Current	I <sub>S</sub>				85	А
Pulsed Current	I <sub>SM</sub>				240	
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = 5 A, V <sub>GS</sub> = 0 V		0.8	1.5	V
Reverse Recovery Time	t <sub>rr</sub>			74	115	ns
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 5 A, dl/dt = 100 A/μs		6.7	10	Α

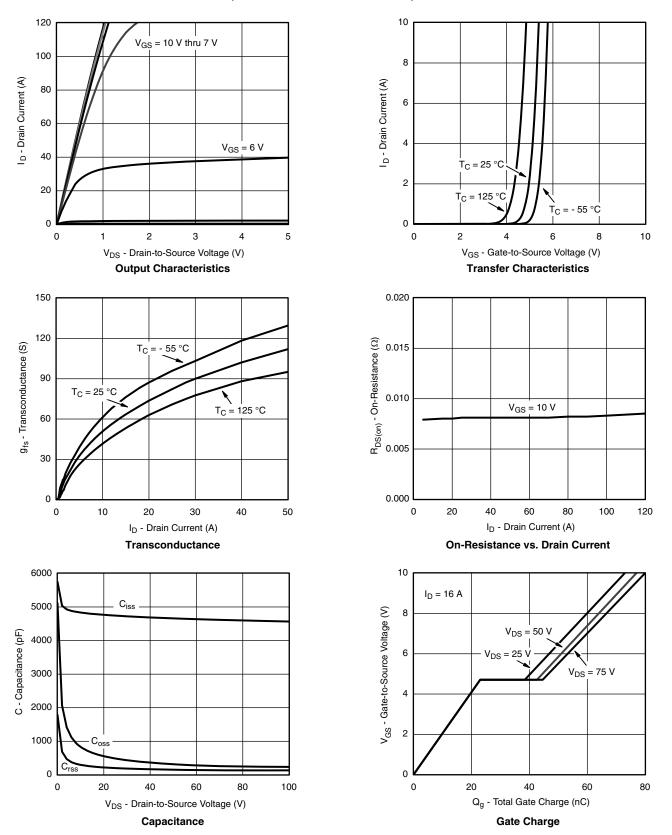
### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

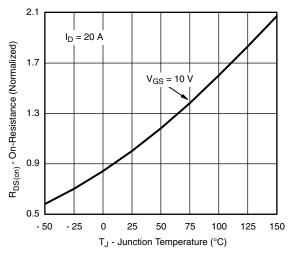
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



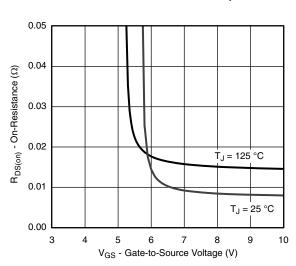
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



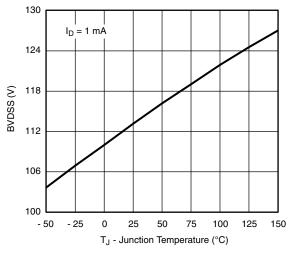
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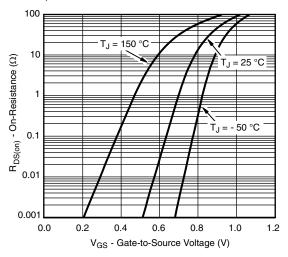
On-Resistance vs. Junction Temperature



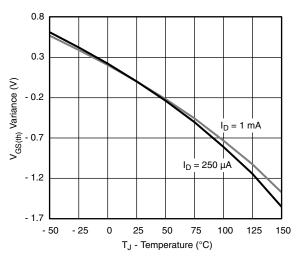
On-Resistance vs. Gate-to-Source Voltage



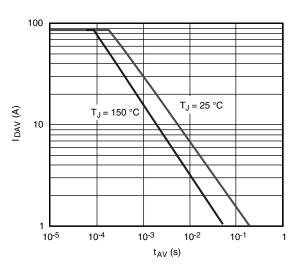
Drain Source Breakdown Voltage vs. Junction Temperature



Source-Drain Diode Forward Voltage



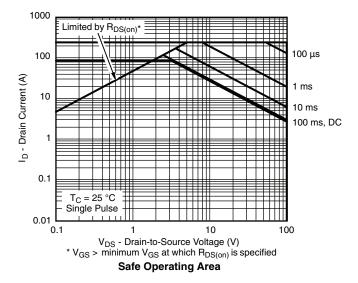
**Threshold Voltage** 

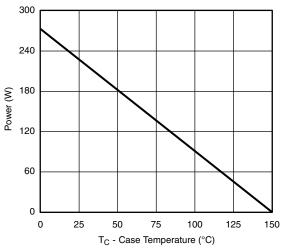


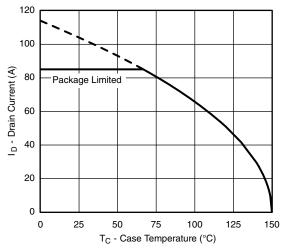
Single Pulse Avalanche Current Capability vs. Time



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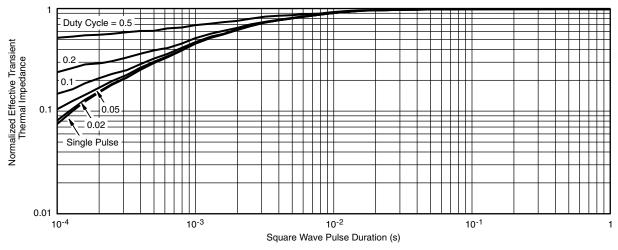
**Current Derating\*** 

Power Derating, Junction-to-Case

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<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heats inking is used. It is used to determine the current rating, when this rating falls below the package limit.

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

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